L Number	Hits	S arch Text	DB	Time stamp
1	751	(((Core and clad$4)) and wave$guide and (mask or hard4mask r etch$ mask)) and (resist r ph t resist)	USPAT; US-PGPUB; DERWENT	2003/02/12 08:53
3	164	((((Core and clad$4)) and wave$guide and (mask or hard4mask or etch$ mask)) and (resist or photoresist)) and (Cr or chrome or chromium)	USPAT; US-PGPUB; DERWENT	2003/02/12 11:08
5	451	((((Core and clad$4)) and wave$guide and (mask or hard4mask or etch$ mask)) and (resist or photoresist)) and $4align$4	USPAT; US-PGPUB; DERWENT	2003/02/12 10:35
7	97	(((((Core and clad$4)) and wave$guide and (mask or hard4mask or etch$ mask)) and (resist or photoresist)) and (Cr or chrome or chromium)) and (align$3 or self$align$3)	USPAT; US-PGPUB; DERWENT	2003/02/12 11:09
8	95	((((((Core and clad$4)) and wave$guide and (mask or hard4mask or etch$ mask)) and (resist or photoresist)) and (Cr or chrome or chromium)) and (align$3 or self$align$3)) and (quartz or silica or SiO2 or Glass)	USPAT; US-PGPUB; DERWENT	2003/02/12 11:10
-	989	(430/321).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 11:31
-	143	(216/25,26).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 15:12
-	882	Wave$guide and micro$machin$4	USPAT; US-PGPUB; DERWENT	2003/02/10 15:30
-	580	(Wave$guide and micro$machin$4) and etch$4	USPAT; US-PGPUB; DERWENT	2003/02/10 15:15
-	35	(Wave$guide and micro$machin$4).clm.	USPAT; US-PGPUB; DERWENT	2003/02/10 16:52
-	49	(Wave$guide and micro$machin$4) and self$align$3	USPAT; US-PGPUB; DERWENT	2003/02/10 15:30
-	218	(Wave$guide and micro$machin$4) and ((Core and clad$4))	USPAT; US-PGPUB; DERWENT	2003/02/10 16:43
-	125	(65/385).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 16:50
-	101	(65/429).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 17:40
-	1095	(385/88).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 16:52
-	19	(Wav $guide and micr $machin$4) and ((385/88).CCLS.)	USPAT; US-PGPUB; DERWENT	2003/02/10 16:59

•	754	(385/129).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 16:59
•	19	(Wave$guid and micr $machin$4) and ((385/129).CCLS.)	USPAT; US-PGPUB; DERWENT	2003/02/10 17:02
•	926	(385/147).CCLS.	USPAT; US-PGPUB; DERWENT	2003/02/10 17:02
•	4	(Wave$guide and micro$machin$4) and ((385/147).CCLS.)	USPAT; US-PGPUB; DERWENT	2003/02/10 17:02
•	250	((Core and clad$4)) and ((385/88).CCLS.)	USPAT; US-PGPUB; DERWENT	2003/02/10 17:41
•	27947	(Core and clad$4)	USPAT; US-PGPUB; DERWENT	2003/02/11 18:06
•	67672	wave$guide	USPAT; US-PGPUB; DERWENT	2003/02/11 18:07
•	464166	mask or hard4mask or etch$ mask	USPAT; US-PGPUB; DERWENT	2003/02/11 18:08
•	3007	((Core and clad$4)) and wave$guide and (mask or hard4mask or etch$ mask)	USPAT; US-PGPUB; DERWENT	2003/02/11 18:09
•	310275	resist or photoresist	USPAT; US-PGPUB; DERWENT	2003/02/11 18:10